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ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar (\$1.00) in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

(1) Jinchuan BAI (2) Chung-Che TSAI

Inventor(s)
Full Name(s)

hereby sell, assign and transfer to

Assignee
Name and
Address

UNITED TEST CENTER INC.
No2. Li-Hsin road, 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C.

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

Title of
Invention

LOW PROFILE SEMICONDUCTOR PACKAGE AND PROCESS FOR MAKING THE SAME

which application was

Complete
either
a) or b)

a) executed by the undersigned on the 10th day of August, 19 2000.
b) filed on the day of , 19

Serial No including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date

Signed at Hsinchu, Taiwan, R.O.C.

this 10th day of August, 19 2000.

Inventor(s)
Full
Signature(s)

INVENTOR(S):

Jinchuan BAI (Jinchuan BAI)
Chung-Che TSAI (Chung-Che TSAI)

Witnesses'
Full
Signatures

WITNESSES: